

What is claimed is:

1. A semiconductor device collecting method for separately collecting a packaged semiconductor device provided on a printed board, comprising the steps of:

5 (a) previously providing predetermined information on a package surface of said semiconductor device which faces said printed board;

(b) dismounting said semiconductor device from said printed board so that said semiconductor device can be separately collected and so that said predetermined information can be seen, and receiving a report based on said predetermined information
10 from the user; and
(c) collecting separated said semiconductor device.

2. The semiconductor device collecting method according to claim 1,

wherein said step (a) comprises a step of providing a service number as said
15 predetermined information on the package surface facing said printed board, and
said step (b) comprises a step of giving a reward for the separate collection to
said user who reported said service number.

3. The semiconductor device collecting method according to claim 2, wherein

20 said step (b) comprises a step of accepting the report about said service number through a communication network.

4. The semiconductor device collecting method according to claim 1,

wherein said step (a) comprises a step of sticking a label as said predetermined
25 information on the package surface facing said printed board, and

TOKYO TOKYO TOKYO

said step (b) comprises a step of giving a reward for the separate collection to said user who sent said label.

5. A method for selling and using a semiconductor device contained in an electrical appliance, comprising the steps of:

(a) selling said electrical appliance to a user in a condition in which said electrical appliance cannot operate without input of predetermined data; and

(b) remotely supplying said predetermined data to said user through a communication network to enable the input to said electrical appliance.

10

6. The semiconductor device selling and using method according to claim 5, wherein said predetermined data comprises code data for approving operation of said electrical appliance.

15

7. The semiconductor device selling and using method according to claim 5, wherein said predetermined data comprises software for a microcomputer which controls operation of said electrical appliance.

20

8. The semiconductor device selling and using method according to claim 5, wherein said step (a) comprises a step of selling said electrical appliance at a predetermined discount determined by considering the price of said semiconductor device, and

25 said step (b) comprises a step (b-1) of, through said communication network, and in exchange for a right to use said semiconductor device, making an agreement about a fee which said user pays to use said semiconductor device and setting said fee which

said user pays to use said semiconductor device.

9. The semiconductor device selling and using method according to claim 8,
wherein said step (b-1) comprises a step of setting said fee for the use of said
5 semiconductor device on the basis of the frequency of use of said electrical appliance.

10. The semiconductor device selling and using method according to claim 9,
wherein said frequency of use of said electrical appliance is calculated on the basis of the
amount of power consumed by said semiconductor device.

10

11. The semiconductor device selling and using method according to claim 9,
wherein said frequency of use of said electrical appliance is calculated on the basis of the
amount of data processed by said semiconductor device.

15

12. The semiconductor device selling and using method according to claim 11,
wherein said amount of data processed by said semiconductor device is calculated by,
in time to a clock signal, comparing present data inputted to said semiconductor
device and previous data preceding said present data by one clock, and

20 incrementing a counter for counting the number of clocks of said clock signal
when said present data and said previous data disagree and calculating said amount of
data on the basis of the total number counted.

TOKUYO-TD20/660